



DT1446-04V

#### 4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

## **Product Summary**

V <sub>BR (min)</sub>	I <sub>PP (max)</sub>	C <sub>T (typ)</sub>
6V	4.7A	0.55pF

### **Description**

The DT1446-04V is a high performance device suitable for protecting four high speed I/Os and one  $V_{\rm CC}$ . These devices are assembled in SOT563 package. They have high ESD surge capability and low capacitance.

## **Applications**

 Typically Used for High Speed Ports such as USB 2.0, IEEE1394, HDMI, Laptop and Personal Computers, Flat Panel Displays, Video Graphics Displays, SIM Ports

## **Features**

- IEC 61000-4-2 (ESD): Air ±19kV, Contact ±16kV
- Low Channel Input Capacitance of 0.55pF Typical
- ESD Protection for four I/Os and one V<sub>CC</sub>
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Mechanical Data**

- Case: SOT563
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Copper leadframe (Lead Free Plating) Solderable per MIL-STD-202, Method208 @3
- Weight: 0.003 grams (approximate)



2.27

Top View Bottom View

Device Schematic

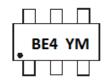
### **Ordering Information** (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DT1446-04V-7	Standard	BE4	7	8	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



BE4 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	2013	2014	2015	2016	2017	2018
Code	А	В	С	D	E	F

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current ,per IEC 61000-4-5	I <sub>PP_I/O</sub>	4.7	Α	I/O to V <sub>SS</sub> , 8/20µs
Operating Voltage (DC)	$V_{DC}$	6	V	V <sub>CC</sub> to V <sub>SS</sub>
ESD Protection – Contact Discharge	$V_{\text{ESD\_I/O}}$	±16	kV	I/O to V <sub>SS</sub> , per IEC 61000-4-2
ESD Flotection – Contact Discharge	$V_{ESD}V_{CC}$	±30	kV	Vcc to V <sub>SS</sub> , per IEC 61000-4-2
ESD Protection – Air Discharge, per IEC 61000-4-2	$V_{\text{ESD\_I/O}}$	±19	kV	I/O to V <sub>SS</sub> , per IEC 61000-4-2
ESD Flotection – All Discharge, per IEC 61000-4-2	$V_{ESD}V_{CC}$	±30	kV	V <sub>CC</sub> to V <sub>SS</sub> , per IEC 61000-4-2

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	$P_{D}$	380	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	$R\theta_{JA}$	327	°C/W
Operating and Storage Temperature Range	$T_{J}, T_{STG}$	-55 to +150	°C

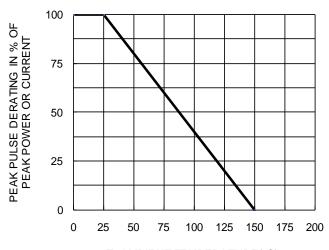
### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	Vrwm	_	_	5.5	V	V <sub>CC</sub> to V <sub>SS</sub>
Reverse Current (Note 6)	I <sub>R(</sub> V <sub>CC to</sub> V <sub>SS)</sub>	_	_	5.0	μΑ	V <sub>R</sub> = 5V, V <sub>CC</sub> to V <sub>SS</sub>
Reverse Current (Note 6)	I <sub>R(IO to</sub> V <sub>SS)</sub>	_	_	1.0	μA	$V_R = 5V$ , any I/O to $V_{SS}$
Reverse Breakdown Voltage	V <sub>BR</sub>	6.0	_	9.0	V	I <sub>R</sub> = 1mA, V <sub>CC</sub> to V <sub>SS</sub>
Forward Clamping Voltage	$V_{F}$	_	0.8	1.0	V	$I_F = 15mA$ , $V_{SS}$ to $V_{CC}$
Reverse Clamping Voltage (Note 7)	$V_{C_{-}I/O}$	_	8.5	_	V	$I_{PP} = 4.7A$ , I/O to $V_{SS}$ , 8/20 $\mu$ s
ESD Clamping Voltage	Vesd_Vcc	_	10	_	V	TLP, 20A, tp = 100 ns, $V_{CC}$ to $V_{SS}$
ESD Clamping Voltage	Vesd_I/O	_	12	_	V	TLP, 20A, tp = 100 ns, I/O to $V_{SS}$
Dynamia Registance	$R_{DIF}V_{CC}$	_	0.2	_	Ω	TLP, 20A, tp = 100 ns, $V_{CC}$ to $V_{SS}$
Dynamic Resistance	R <sub>DIF_I/O</sub>	_	0.3	_	Ω	TLP, 20A, tp = 100 ns, I/O to V <sub>SS</sub>
Channel Input Capacitance	$C_{I/O \ to} \ V_{SS}$	_	0.55	0.65	pF	$V_R = 2.5V, V_{CC} = 5V, f = 1MHz$
Channel Input Capacitance	C <sub>I/O to</sub> V <sub>SS</sub>		0.65	_	pF	V <sub>R</sub> = 2.5V, V <sub>CC</sub> = floating, f = 1MHz
Variation of Channel Input Capacitance	CI/OMAX-CI/OMIN	_	0.03	_	pF	V <sub>CC</sub> = 5V, V <sub>SS</sub> = 0V, I/O = 2.5V, f =1MHz, T=25 °C, C <sub>I/OMAX</sub> -C <sub>I/OMIN</sub>
Variation of Channel Input Capacitance	CI/OMAX-CI/OMIN	_	0.05	_	pF	$V_{CC}$ = floating , $V_{SS}$ = 0V, I/O = 2.5V, f =1MHz, T = +25°C , $C_{I/OMAX}$ - $C_{I/OMIN}$

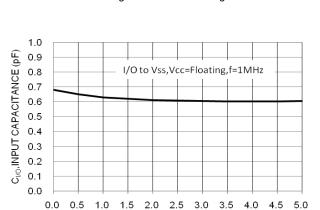
Notes:

- 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.
- 6. Short duration pulse test used to minimize self-heating effect.
- 7. Clamping voltage value is based on an  $8x20\mu s$  peak pulse current ( $I_{pp}$ ) waveform.

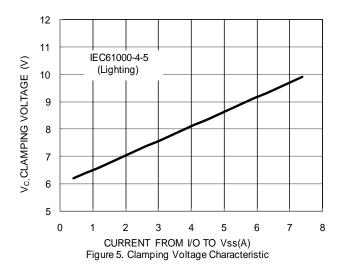


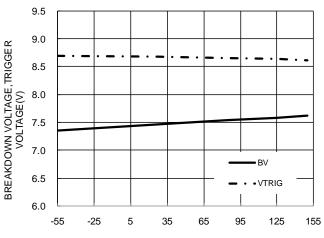


T<sub>A</sub>,AMBIENT TEMPERATURE(°C) Figure1. Pulse Derating Curve

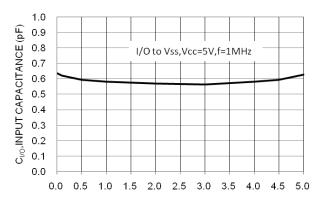


V<sub>I/0,</sub> INPUT VOLTAGE (V) Figure 3. Input Capacitance vs. Input Voltage





T<sub>A</sub>, AMBIENT TEMPERATURE (°C) Figure 2. BV, Trigger Voltage vs. Ambient Temperature



V<sub>I/O,</sub> INPUT VOLTAGE (V) Figure 4. Input Capacitance ∨s. Input Voltage

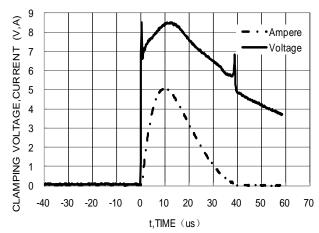
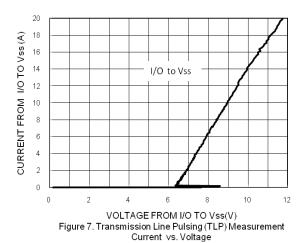


Figure 6. Waveform of Clamping Voltage, Current vs. Time(8/20us, I/O to Vss)

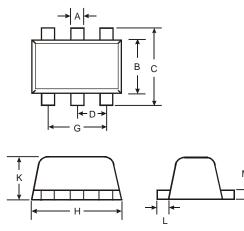




VOLTAGE FROM Vcc TO Vss(V)
Figure 8. Transmission Line Pulsing (TLP) Measurement
Current vs. Voltage

# **Package Outline Dimensions**

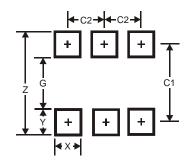
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SOT563								
Dim	Min	Max	Тур						
Α	0.15	0.30	0.20						
В	<b>B</b> 1.10		1.20						
С	1.55	1.70	1.60						
D	-	-	0.50						
G	0.90	1.10	1.00						
Н	1.50	1.70	1.60						
K	0.55	0.60	0.60						
L	0.10	0.30	0.20						
М	0.10	0.18	0.11						
All	Dimens	sions in	mm						

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Υ	0.5
C1	1.7
C2	0.5



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